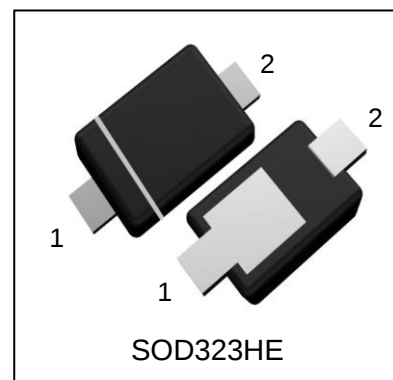


S-LMBR140ET1G

Schottky Barrier Diode

1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Low power loss,high efficiency.
- For use in low voltage high frequency inverters,free wheeling,and polarity protection applications.
- Guardring for over voltage protection.
- High temperature soldering guaranteed:260°C/10 seconds at terminals.



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
S-LMBR140ET1G	14	5000/Tape&Reel

3. MAXIMUM RATINGS(Ta = 25°C)

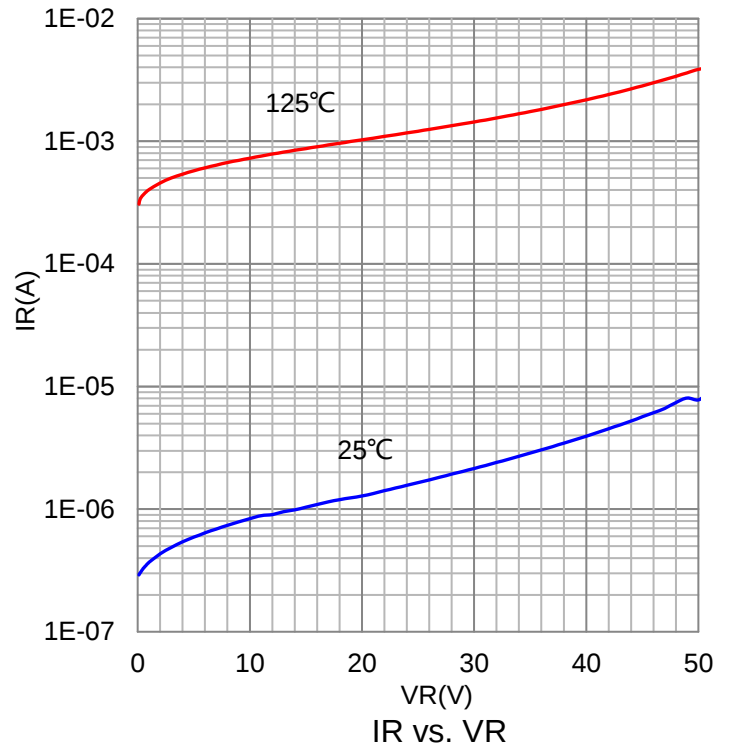
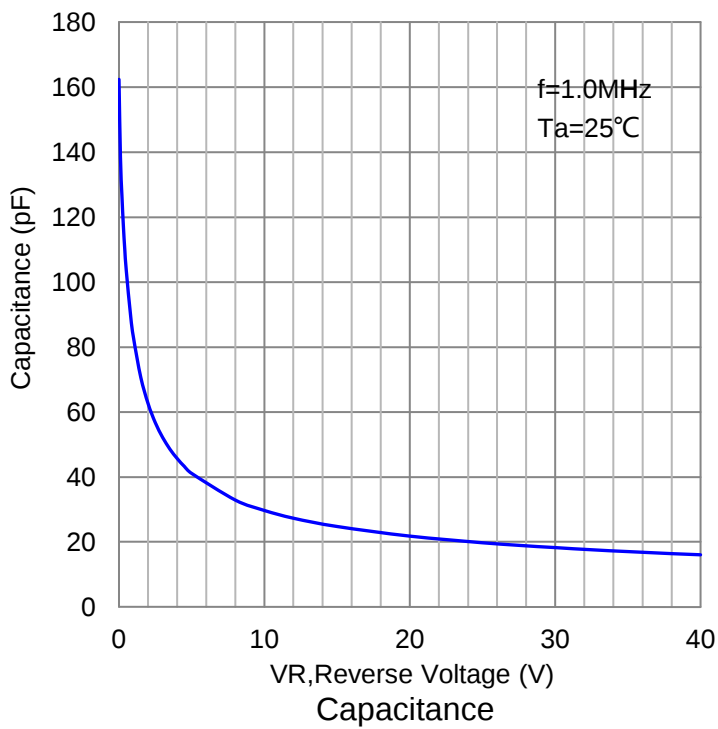
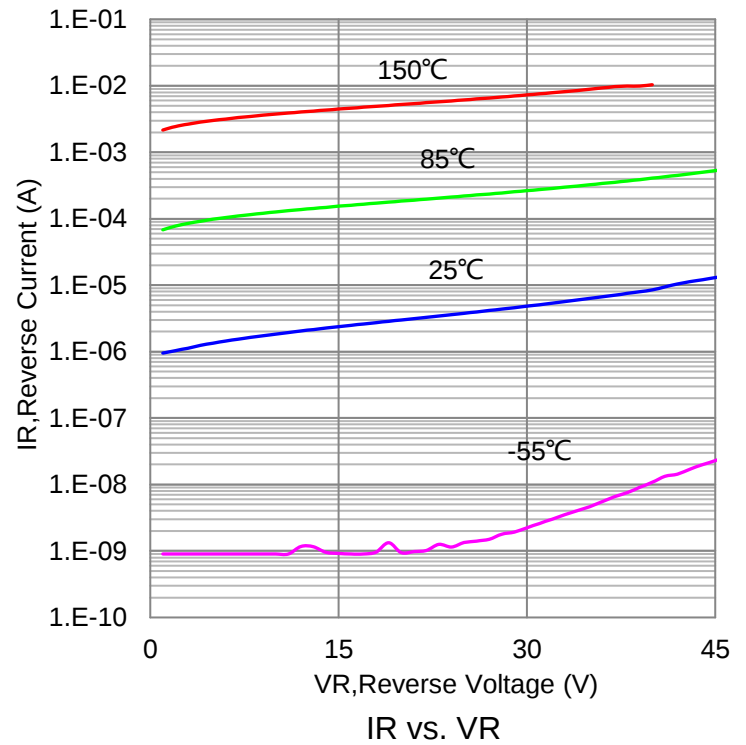
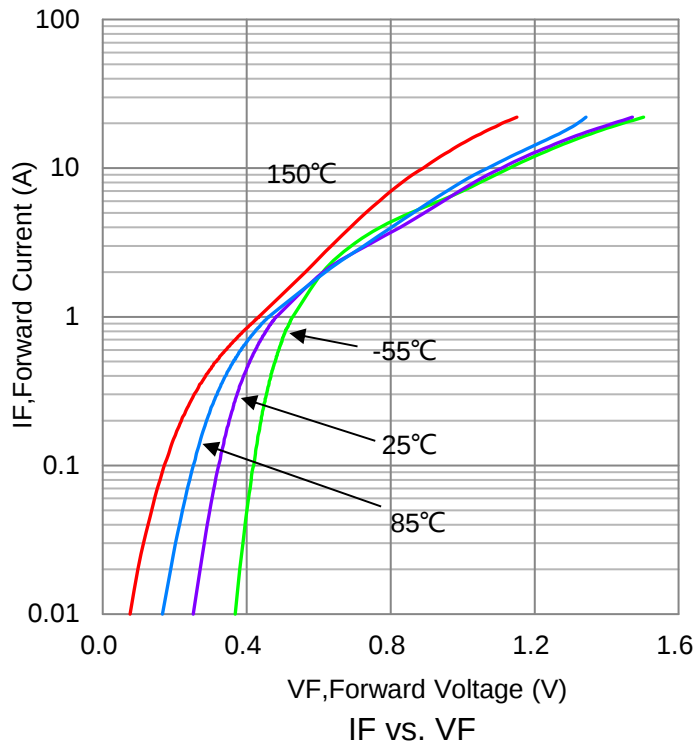
Parameter	Symbol	Limits	Unit
Maximum repetitive peak reverse voltage	VRRM	40	V
Maximum RMS voltage	VRMS	28	V
Maximum DC blocking voltage	VDC	40	V
Maximum average forward rectified current at TC = 75°C	IF(AV)	1	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	22	A
Total Device Dissipation, FR-4 Board (Note 1) @ TA = 25°C	PD	817	mW
Typical thermal resistance (Note 1)	RθJA	153	°C/W
	RθJC	34	
Operating junction temperature range	TJ	-55 ~ +150	°C
storage temperature range	TSTG	-55 ~ +150	°C

1. 30.0mm×25.0mm×1.6mm(FR4), Copper foil thickness 35μm;

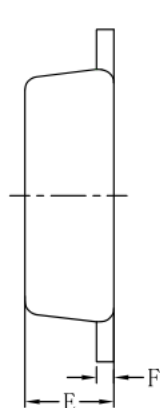
4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Maximum instantaneous forward (IF =0.7 A, TJ = 25°C)	VF	-	-	0.48	V
(IF = 1.0 A, TJ = 25°C)		-	-	0.55	
Maximum DC reverse current at rated DC blocking voltage TA = 25°C	IR	-	5	30	uA
TJ = 125°C		-	2.5	10	mA
Typical junction capacitance at 4.0V, 1MHz	CJ	-	50	-	pF

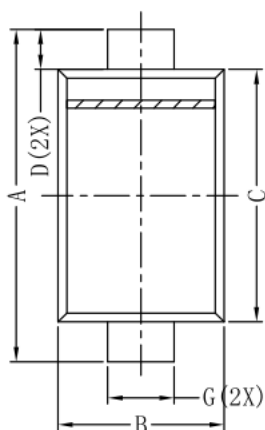
5. ELECTRICAL CHARACTERISTICS CURVES



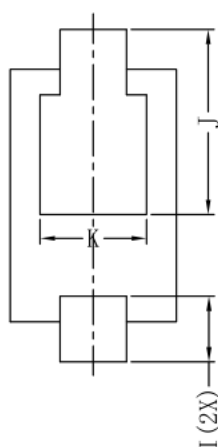
6.OUTLINE AND DIMENSIONS



SIDE VIEW



TOP VIEW



BOTTOM VIEW

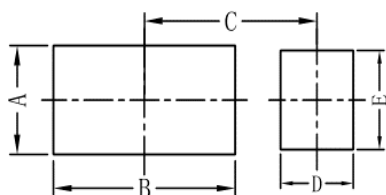
SOD323HE			
DIM	MIN	MAX	Typ.
A	2.30	2.70	2.55
B	1.20	1.35	1.25
C	1.75	1.95	1.90
D	-	-	0.30
E	0.55	0.75	0.67
F	0.10	0.20	0.15
G	0.45	0.65	0.50
I	0.40	0.70	0.50
J	1.15	1.55	1.40
K	-	-	0.80
All Dimensions in mm			

GENERAL NOTES

- 1.Top package surface finish $Ra0.4 \pm 0.2\mu m$
- 2.Bottom package surface finish $Ra0.7 \pm 0.2\mu m$

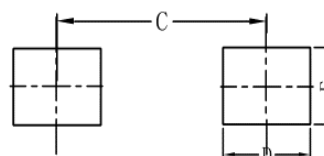
7.SOLDERING FOOTPRINT

RECOMMENDED PAD



SOD323HE	
DIM	(mm)
A	1.1
B	2.0
C	1.9
D	0.8
E	1.0

COMPATIBLE PAD



SOD323HE	
DIM	(mm)
D	1.0
E	0.8
C	2.4

DISCLAIMER

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
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